

REMARKS

Claims 1, 2, 5, 6, 9, 10, 13 and 14 have been canceled without prejudice or disclaimer. No claims have been amended or added. Accordingly, claims 3, 4, 7, 8, 11, 12, 15 and 16 are currently pending in the application.

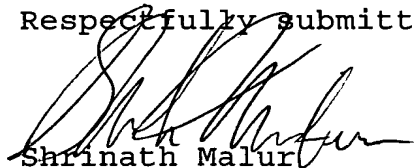
Enclosed is a certified copy of the foreign priority document (JP No. 11-275730, filed 9/29/99). Applicants request the Examiner to acknowledge the claim for priority and safe receipt of this document.

The specification and Abstract have been amended to cure minor informalities. No new matter has been added.

Claims 1, 2, 5 and 6 stand rejected under 35 U.S.C. §102 as being anticipated by Miyagawa et al. Claims 1, 2, 5, 6, 9 and 10 stand rejected under 35 U.S.C. §102 as being anticipated by Fujita et al. Claims 1, 2, 5, 6, 9 and 10 stand rejected under 35 U.S.C. §102 as being anticipated by Eda et al. Finally, claims 13 and 14 stand rejected under 35 U.S.C. §103 as being unpatentable over Miyagawa et al in view of Ohnuki et al. These rejections have been rendered moot in view of the cancellation of claims 1, 2, 5, 6, 9, 10, 13 and 14 without prejudice or disclaimer in order to expedite the issuance of subject matter indicated as being allowable.

In view of the foregoing amendments and remarks, Applicants contend that the above-identified application is now in condition for allowance. Accordingly, reconsideration and reexamination are respectfully requested.

Respectfully submitted,



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**MARKED UP VERSION OF REPLACED
PARAGRAPHS OF THE SPECIFICATION**

Page 1, first full paragraph (lines 6-9), the marked up paragraph is as follows:

The present invention relates to a high frequency circuit module and a communication device such as a mobile wireless terminal and a pocket telephone [using it] employing the same.

Page 1, second full paragraph (lines 11-15), the marked up paragraph is as follows:

The miniaturization and the enhancement of the efficiency of power of a high frequency circuit module used for a mobile wireless terminal, a pocket telephone and others in view of the mountability and talk time have been [an] important objectives.

Pages 2 and 3, the paragraph bridging these pages from page 2, line 13 to page 3, line 10, the marked up paragraph is as follows:

Also, an example of a high frequency circuit module using a multi-layer (two-layer) dielectric substrate is shown in the proceeding of the 1997 Institute IEIC Conference Electronics Society C-2-14, "1.9 GHz RF Front-End Module Using a Ceramics

Substrate" (hereinafter called second conventional technique). According to the second conventional technique, a transmission line which is a distributed constant element, an input-output matching circuit composed of a lumped constant element such as a resistor, a capacitor and an inductor and a semiconductor element are formed on the same surface of a dielectric substrate to compose a high frequency circuit module. A high frequency signal electrode provided to the surface of a first layer of the dielectric substrate and a high frequency signal electrode on the reverse side of a second layer are connected via wiring provided to the surface of the second layer through a through-hole. The earth electrode of the semiconductor element provided to the surface of the first layer of the dielectric substrate and an earth electrode on the reverse side are connected via a through-hole. The order of the layers of the dielectric substrate are counted as a first layer, a second layer, a third layer, [---] etc., from the surface to the reverse side.

Page 8, eighth full paragraph (lines 25-26), the marked up paragraph is as follows:

The present invention will be [detailedly] described in detail based upon embodiments below.